

SGP.15a

Specification

Part No.	SGP.1575.15.4.A.02
Product Name	GPS SMT Patch Antenna
Feature	15mm*15mm*4.5mm 1575MHz Centre Frequency Patent Pending RoHS Compliant



1. Introduction

This ceramic GPS patch antenna is based on smart **XtremeGain™** technology. It is mounted via SMT process and has been selected as optimal solution for the 45x45mm ground plane.

2. Specification

NO	PARAMETER	SPECIFICATION	NOTES
1	Range of Receiving Frequency	1575.42 MHz ± 1.023 MHZ	
2	Center Frequency	1575.42 ± 3MHz	With 45*45mm Ground Plane
3	Bandwidth	6MHz min	Return Loss ≤-10 dB
4	VSWR	1.5 max	
5	Gain at Zenith	+1.0 dBic typ.	
6	Gain at 10°elevation	-	
7	Axial Ratio	3.0 dB max	
8	Polarization	RHCP	
9	Impedance	50 Ohms	
10	Frequency Temperature Coefficient (Tf)	0 ± 20ppm / °C	-40°C to +85°C
11	Operating Temperature	-40°C to +85°C	

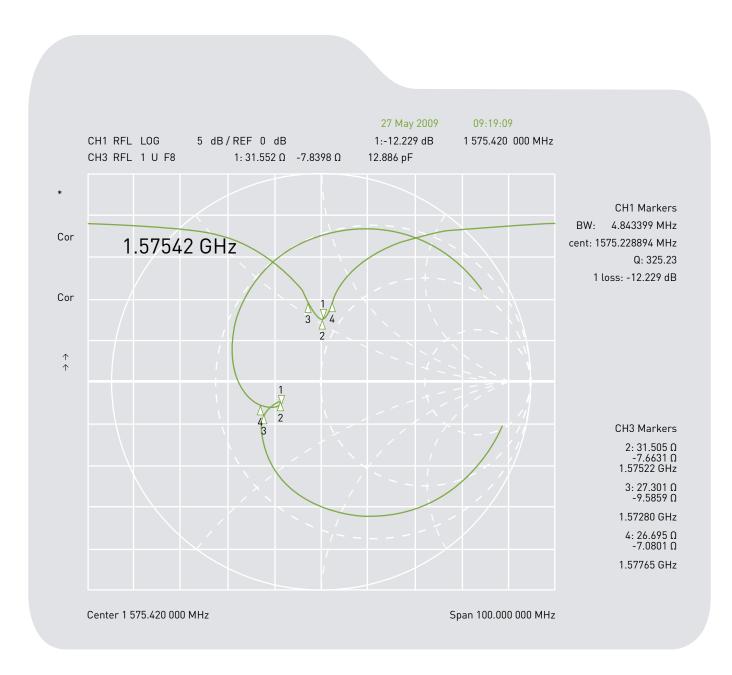
Original Patch Specification tested on 45mm ground plane

**Changes in user groundplane and environment will offset centre frequency



3. Electrical Specifications

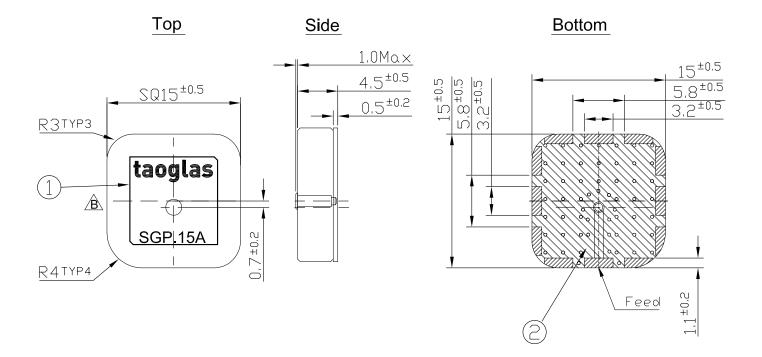
3.1 Return Loss, SWR, Impedance, measured on the test fixture





4. Mechanical Specifications

4.1 Dimensions and Drawing



NOTE:

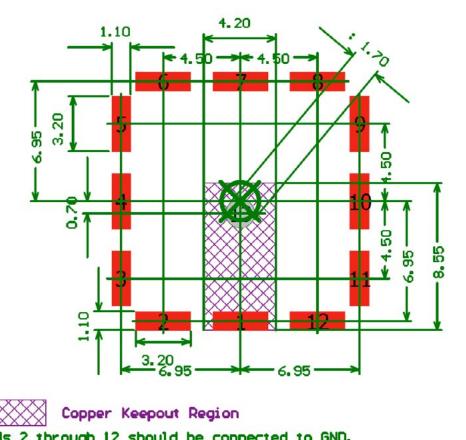
- 1. Solder mask.
- 2. Area to be soldered.
- 3. Clearance area.
- **4.** Dimension of 50 Ohm CPW dependent on individual board.
- **5.** Must be soldered to complete antenna feed connection.

	Name	Part No.	Material	Finish	Quantity
1	SGP.15 Patch 15x15x4	SGP.15	Ceramic	Clear	1
2	SGP.15 PCB		FR4 0.5t	Green	1



4.2 Antenna Footprint

4.2.1 Top Copper



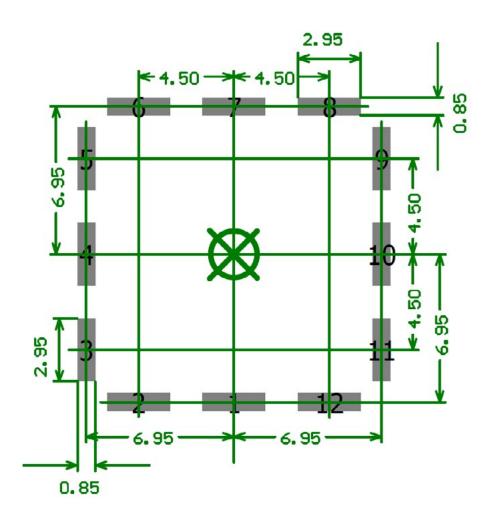
Dimensions in mm

Pads 2 through 12 should be connected to GND. Pad 13 is a 1.70mm dia. non-plated thru-hole. Connect 50 ohm transmission line to Pad 1. Copper Keepout Region should extend at least 2 mm down into PCB.



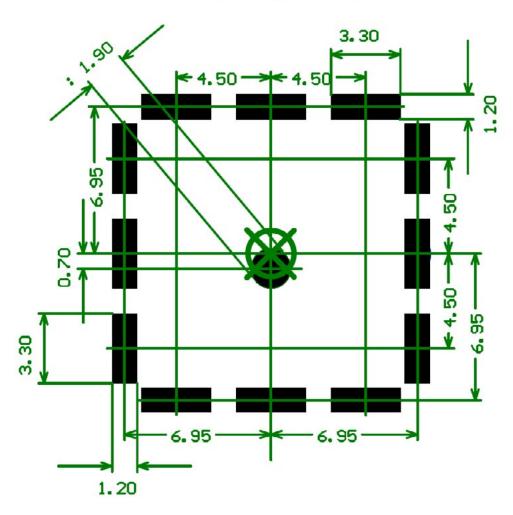
4.2.2 Top Paste







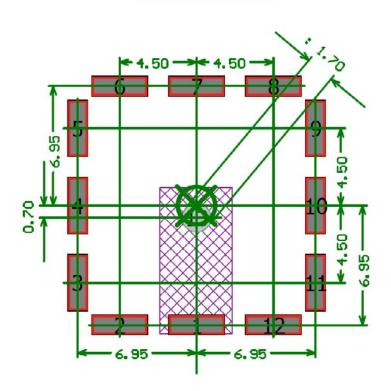
4.2.3 Top Mask



Dimensions in mm



4.2.4 Composite

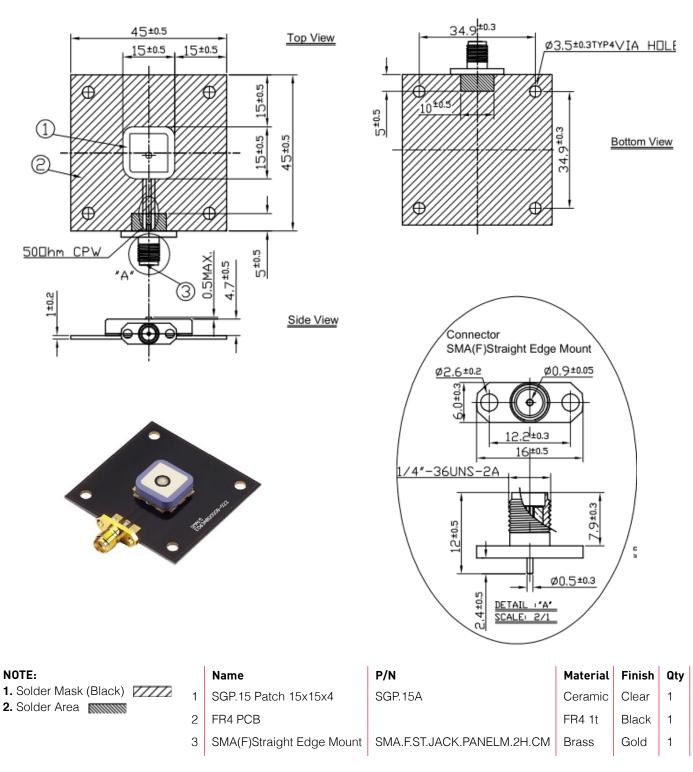


Dimensions in mm

Copper Keepout Region

Pads 2 through 12 should be connected to GND. Pad 13 is a 1.70mm dia. non-plated thru-hole. Connect 50 ohm transmission line to Pad 1. Copper Keepout Region should extend at least 2 mm down into PCB.

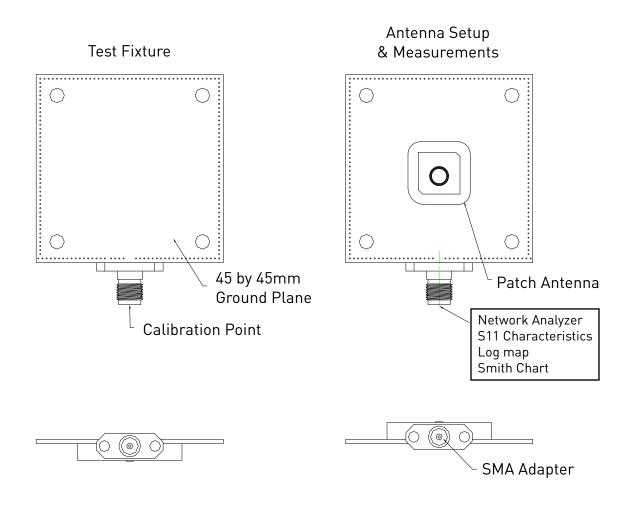




4.3 Test Jig and Dimension



4.4 Test Fixture set up and measurements

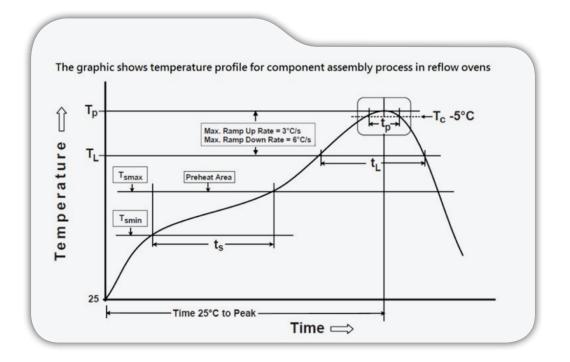




5. Recommended Reflow Soldering Profile

SGP.15A can be assembled following Pb-free assembly. According to the Standard IPC/JEDEC J-STD-020C, the temperature profile suggested is as follow:

PHASE	PROFILE FEATURES	Pb-Free Assembly (SnAgCu)
PREHEAT	Temperature Min(Tsmin)	150°C
	Temperature Max(Tsmax)	200°C
	Time(ts) from (Tsmin to Tsmax)	60-120 seconds
RAMP-UP	Avg. Ramp-up Rate (Tsmax to TP)	3°C/second(max)
REFLOW	Temperature(TL)	217°C
	Total Time above TL (tL)	30-100 seconds
PEAK	Temperature(TP)	260°C
	Time(tp)	2-5 seconds
RAMP-DOWN	Rate	3°C/second(max)
Time from 25°C to Peak Temperature		8 minutes max.
Composition of solder paste		96.5Sn/3Ag/0.5Cu
Solder Paste Model		SHENMAO PF606-P26



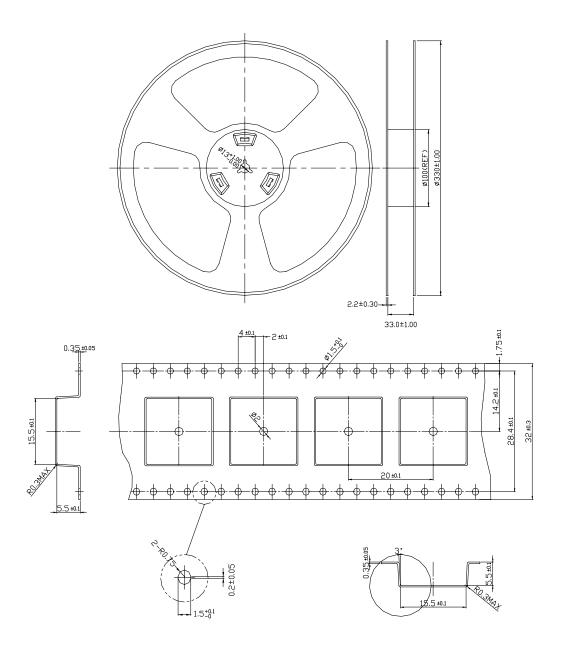
Soldering Iron condition: Soldering iron temperature 270°C±10°C.

Apply preheating at 120°C for 2-3 minutes. Finish soldering for each terminal within 3 seconds, if soldering iron temperature over 270°C±10°C or 3 seconds, it will make cause component surface peeling or damage.



6. Packaging

200 pcs per reel / inner carton 4 reels per outer carton - 800 pcs



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